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PATENT Docket No.

# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT:

**SERGEY LOPATIN** 

ALEXANDER H. NICKEL JOFFRE F. BERNARD

SERIAL NO .:

10/082,433

EXAMINER: UNASSIGNED

FILED:

**FEBRUARY 22, 2002** 

ART UNIT 1741

METHOD OF CONTROLLING ZINC-DOPING IN A COPPER-ZINC ALLOY THIN FILM ELECTROPLATED ON A COPPER SURFACE

AND A SEMICONDUCTOR DEVICE THEREBY FORMED

# COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

### TRANSMITTAL LETTER

Dear Sir:

In connection with the above referenced patent application, transmitted herewith are the following:

- 1. Information Disclosure Statement (1 pages);
- 2. Information Disclosure Statement By Applicant Form PTO-1449 (1 page);
- 3. U.S. Patent No. 6,197,181 B1 (18 pages);
- 4. U.S. Patent No. 6,022,808 (6 pages);
- 5. Article "A Practical Guide to Semiconductor Processing" (3 pages);
- 6. Article "Electrochemical Codeposition and Electrical Characterization of a Copper-Zinc Alloy Metallization" (2 pages);
- 7. Article "Using Electrochemistry to Improve Copper Interconnect" (4 pages);
- 8. Article "ECD Seed Layer for Inlaid Copper Metallization" (2 pages); and

9. Post card in acknowledgment of receipt of all transmitted materials.

Please date-stamp the enclosed postcard and return same to the undersigned in acknowledgment of receipt of all transmitted material.

Respectfully submitted,

Victor Flores

Reg. No. 29,638

VF/sgs June 14, 2002 LARIVIERE, GRUBMAN & PAYNE, LLP P.O. Box 3140 Monterey, CA 93942 (831) 649-8800 Express Mail" mailing label number: EV133912612US

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Signature:

**PATENT** Docket No. P1408

### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT:

SERGEY LOPATIN

ALEXANDER H. NICKEL JOFFRE F. BERNARD

SERIAL NO.:

10/082,433

**EXAMINER: UNASSIGNED** 

FILED:

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**FEBRUARY 22, 2002** 

**ART UNIT** 

1741

FOR:

METHOD OF CONTROLLING ZINC-DOPING IN A COPPER-ZINC ALLOY THIN FILM ELECTROPLATED ON A COPPER SURFACE

AND A SEMICONDUCTOR DEVICE THEREBY FORMED

**COMMISSIONER FOR PATENTS** WASHINGTON, D.C. 20231

#### INFORMATION DISCLOSURE STATEMENT

Applicant hereby makes available the references listed on the enclosed form PTO-1449, Information Disclosure Statement by Applicant to assist the Patent and Trademark Office in its examination of this application.

The disclosure of the references does not constitute an admission that they are relevant or material to the claims or are "prior art" to the subject application. No representation is made that better references do not exist. Complete copies of the references are enclosed.

Respectfully submitted,

Reg. No. 29,638

VF/sgs June 14, 2002 LARIVIERE, GRUBMAN & PAYNE, LLP PO Box 3140 Monterey, CA 93942 (831) 649-8800

Substitute for FORM PTO-1449 U.S. Department of Commerce Patent and Trademark Office Patent and Trademark Office PATENT AND ADMINISTRATION DISCLOSURE STATEMENT			Application Number	10/082,433	
			Office RE STATEMENT	Filing Date	2/22/2002
	<u> </u>	BY APPLICANT (Use several sheets if necessary)		First Named Inventor	Sergey Lopatin
Sheet 1 of 1				Attorney Docket No.	P1408
			U.S. PATENT DOCUMENT	s	
Examiner Initial	CiteNo.	U.S. Patent Document Number	Name of Patentee or Applicant of Cited Documents	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages o Relevant Figures Appear
	1	6,197,181 B1	Chen, Lin Lin	3/6/2001	R 1700
	2	6,022,808	Nogami, et al.	2/8/2000	
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		I	FOREIGN PATENT DOCU	MENTS	
Examiner Initials'	Cite No.	Foreign Patent Document Office Number Code	Name of Patentee or Applicant of Cited document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Line Where Relevant Passages or Relevan Figures Appears
	<del></del>	OTHER PRIOR A	ART - NON PATENT LITE	RATURE DOCUMENT	S
Examiner Initials'	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article ( when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.			
	1	PETER VAN ZANT, "Microchip Fabrication: A Practical Guide to Semiconductor Processing", 3 <sup>rd</sup> Ed., p. 392 and 397 (1997)			
	2	A. Krishnamoorthy, D. Duquette and S. Murarka, "Electrochemical Codeposition and Electrical Characterization of a Copper-Zinc Alloy Metallization", in edited by Adricacos, et al., Electrochem Society Symposium Proceedings, Vol. 99-9, May 3-6, Seattle, p. 212			
	3	J. Cunningham, "Using Electrochemistry to Improve Copper Interconnect", in Semiconductor International, Spring 2000 (May)			
	4	L. Chen and T. Ritzdorf, "ECD Seed Layer for Inlaid Copper Metallization" in edited by Andricacos, et al., Electrochem Society Proceedings, Vol. 99-9, May 3-6, Seattle, p. 122			
	<u> </u>				

<sup>1</sup>Unique citation designation number. <sup>2</sup>See attached Kinds of U.S. Patent Documents. <sup>3</sup>Enter Office that issued the document, by the two-letter code (WIPO StandardST.3). <sup>4</sup>For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. <sup>5</sup>Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup>Applicant is to place a check mark here if English Language Translation is attached.